



### DMTH10H1M7STLW

# 100V 175°C N-CHANNEL ENHANCEMENT MODE MOSFET POWERDI1012-8

## **Product Summary**

BVDSS	R <sub>DS(ON)</sub> Max	I <sub>D</sub> Tc = +25°C	
100V	2mΩ @ V <sub>GS</sub> = 10V	250A	

# **Description and Applications**

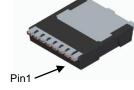
This new generation N-Channel enhancement mode MOSFET is designed to minimize RDS(ON) yet maintain superior switching performance. This device is ideal for use in notebook battery power management and load switch.

### **Applications**

- Motor Control
- DC-DC Converters
- Power Management

#### POWERDI1012-8





Top View

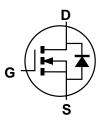
**Bottom View** 

#### **Features**

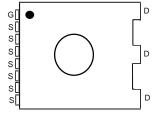
- Rated to +175°C Ideal for High Ambient Temperature Environments
- 100% Unclamped Inductive Switching (UIS) Test in Production Ensures More Reliable and Robust End Application
- High Conversion Efficiency
- Low R<sub>DS(ON)</sub> Minimizes On State Losses
- Wettable Flank for Improved Optical Inspection
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative. https://www.diodes.com/quality/product-definitions/

### **Mechanical Data**

- Case: POWERDI1012-8
- Case Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminals: Finish Matte Tin Annealed over Copper Leadframe.
   Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.388 grams (Approximate)







Top View Pin Configuration

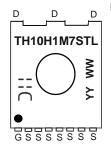
### Ordering Information (Note 4)

Part Number	Case	Packaging
DMTH10H1M7STLW-13	POWERDI1012-8	1,500/Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

### **Marking Information**



#### POWERDI1012-8

⊃¦¦= Manufacturer's Marking TH10H1M7STL = Product Type Marking Code YYWW = Date Code Marking YY = Last Two Digits of Year (ex: 21 = 2021) WW = Week Code (01 to 53)



# **Maximum Ratings** (@ $T_A = +25^{\circ}C$ , unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage	VDSS	100	V	
Gate-Source Voltage	Vgss	±20	V	
Continuous Drain Current (Note 6) $V_{GS} = 10V$ $T_{C} = +25^{\circ}C$ $T_{C} = +100^{\circ}C$		ΙD	250 176	Α
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	I <sub>DM</sub>	1000	Α	
Maximum Continuous Body Diode Forward Current (Note 6)	Is	250	Α	
Pulsed Body Diode Forward Current (10µs Pulse, Duty Cycle = 1%)		lsм	1000	Α
Avalanche Current, L = 0.3mH	las	73	Α	
Avalanche Energy, L = 0.3mH	E <sub>AS</sub>	799.4	mJ	

### **Thermal Characteristics**

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5) T <sub>A</sub> = +25°C		PD	6	W
Thermal Resistance, Junction to Ambient (Note 5)		Reja	24	°C/W
Total Power Dissipation (Note 6) $T_C = +25^{\circ}C$		Pp	214	W
Thermal Resistance, Junction to Case (Note 6)		Rejc	0.6	°C/W
Operating and Storage Temperature Range		TJ, TSTG	-55 to +175	°C

# **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

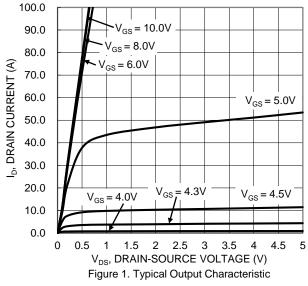
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	100	1	_	V	$V_{GS} = 0V$ , $I_D = 1mA$	
Zero Gate Voltage Drain Current	IDSS	l	1	1	μΑ	V <sub>DS</sub> = 80V, V <sub>GS</sub> = 0V	
Gate-Source Leakage	Igss	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	Vgs(TH)	2	1	4	V	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$	
Static Drain-Source On-Resistance	Rds(on)	_	1.4	2	mΩ	Vgs = 10V, ID = 30A	
Diode Forward Voltage	VsD	1	0.8	1.2	V	V <sub>G</sub> S = 0V, I <sub>S</sub> = 30A	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	Ciss	1	9871	_		V <sub>DS</sub> = 50V, V <sub>GS</sub> = 0V, f = 1MHz	
Output Capacitance	Coss	_	3019	_	pF		
Reverse Transfer Capacitance	C <sub>rss</sub>	_	58	_			
Gate Resistance	$R_g$	_	2.5	_	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$	
Total Gate Charge	Qg	_	147	_		V 50V L 00A	
Gate-Source Charge	Qgs	_	43	_	nC	V <sub>DD</sub> = 50V, I <sub>D</sub> = 30A, V <sub>GS</sub> = 10V	
Gate-Drain Charge	Q <sub>gd</sub>	_	32	_			
Turn-On Delay Time	t <sub>D</sub> (ON)	_	29	_		$V_{DD} = 50V, V_{GS} = 10V,$ $I_{D} = 30A, R_{g} = 4.7\Omega$	
Turn-On Rise Time	t <sub>R</sub>	_	64	_	ns		
Turn-Off Delay Time	tD(OFF)	_	108	_	ns		
Turn-Off Fall Time	tF	_	69	_			
Reverse Recovery Time	t <sub>RR</sub>	_	91	_	ns I OFA JULIU 400A		
Reverse Recovery Charge	Qrr	_	270	_	nC	I <sub>F</sub> = 25A, di/dt = 100A/μs	

5. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.

6. Thermal resistance from junction to soldering point (on the exposed drain pad).7. Short duration pulse test used to minimize self-heating effect.8. Guaranteed by design. Not subject to product testing.







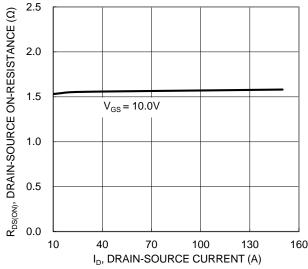


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

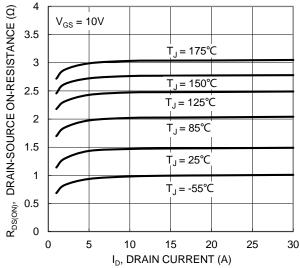
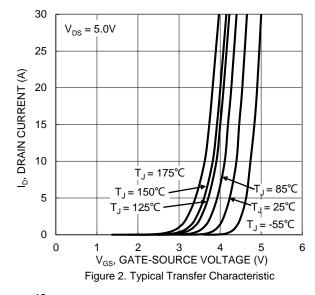
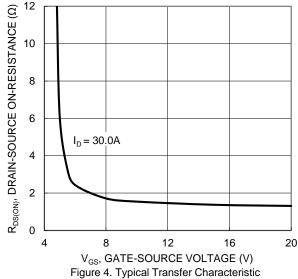


Figure 5. Typical On-Resistance vs. Drain Current and Temperature





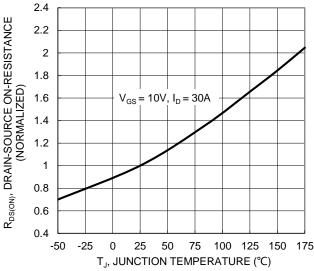


Figure 6. On-Resistance Variation with Temperature





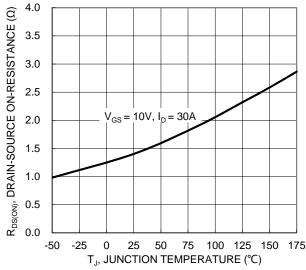


Figure 7. On-Resistance Variation with Temperature

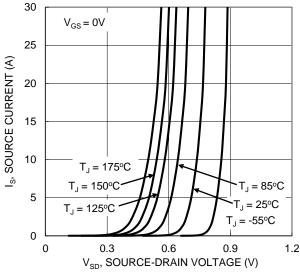
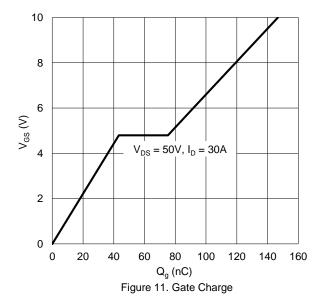


Figure 9. Diode Forward Voltage vs. Current



4  $V_{GS(TH)},$  GATE THRESHOLD VOLTAGE (V) 3.5  $I_D = 1 \text{mA}$ 3 2.5  $I_D = 250 \mu A$ 2 1.5 1 0.5 0 -50 -25 0 25 50 75 100 125 150 175 T<sub>J</sub>, JUNCTION TEMPERATURE (°C)

Figure 8. Gate Threshold Variation vs. Junction Temperature

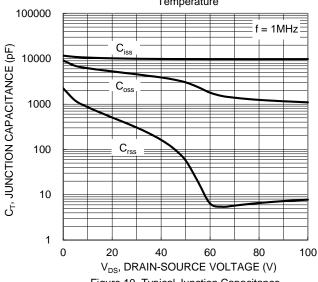
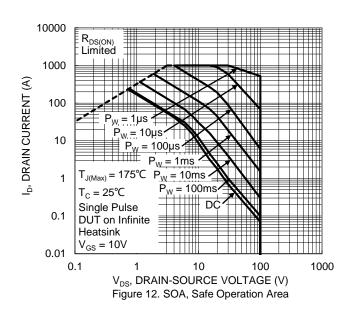


Figure 10. Typical Junction Capacitance





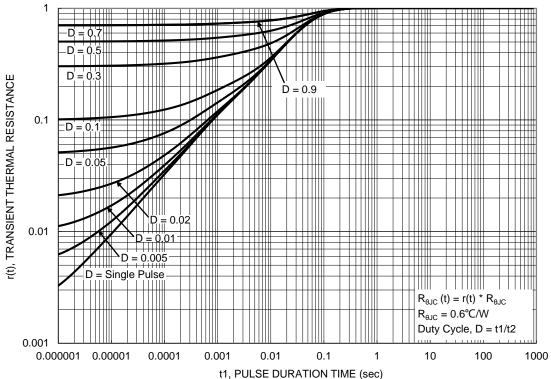


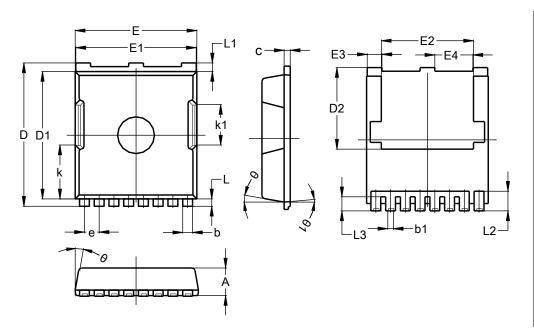
Figure 13. Transient Thermal Resistance



# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### POWERDI1012-8

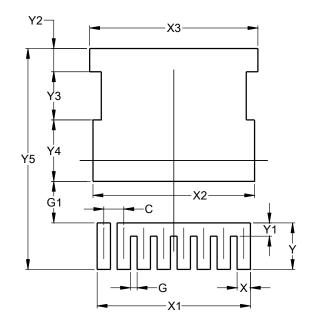


POWERDI1012-8				
Dim	Min	Max	Тур	
Α	2.20	2.40	2.30	
b	0.70	0.90	0.80	
b1	0.42	0.50	0.45	
С	0.40	0.60	0.50	
D	11.48	11.88	11.68	
D1	10.23	10.53	10.38	
D2	6.45	6.85	6.65	
E	9.70	10.10	9.90	
E1	9.70	9.90	9.80	
E2	7.00	8.00	7.50	
E3	1.10	1.30	1.20	
E4	3.00	3.20	3.10	
е	1.20 BSC			
k	4.39 REF			
k1	Ţ	3.30 REF	=	
L	0.50	0.70	0.60	
L1	0.50	0.90	0.70	
L2	1.40	1.80	1.60	
L3	1.00	1.30	1.15	
θ	0°	15º	10°	
θ1	00	10°	5º	
All Dimensions in mm				

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### POWERDI1012-8



Dimensions	Value (in mm)		
С	1.200		
G	0.400		
G1	2.500		
Х	0.800		
X1	9.200		
X2	9.700		
Х3	10.100		
Υ	2.800		
Y1	0.800		
Y2	1.400		
Y3	2.900		
Y4	3.700		
Y5	13.300		



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